Material Composition Data

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Timing Is Everything

HC49 - Standard Cr	yotai				Sub-Assembly
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	% by mass
Base Header	Chaol	Γ-		252.740	00.44
	Steel	Fe		358.748	96.44
		C	7440.04.0	0.179	0.05
		Si	7440-21-3	0.037	0.01
	O	Mn	7439-96-5	0.611	0.16
	Chemical Plating	Ni -	7440-02-0	3.814	1.03
		P 	7723-14-0	0.371	0.10
	Electro Plating	Ni	7440-02-0	8.240	2.22
Base clip	Copper Alley	Cu	7440 50 0	7.014	E2 0E
	Copper Alloy	Cu Ni	7440-50-8	7.014	53.95
			7440-02-0	2.149	16.53
		Fe	7439-89-6	0.035	0.27
		Mn Za	7439-96-5	0.071	0.55
D Ol		Zn	7440-66-6	3.731	28.70
Base Glass	Hard Glass	Tridymite	7440-28-0	11.900	82.01
	i latu Glass	Aluminium Oxide	1344-28-1	1.570	10.82
		Disodium-oxide	7440-50-8	0.800	5.51
			7440-50-8 7440-50-8	0.800	1.65
Base terminal wire		Dipotassium-oxide	7440-30-6	0.240	1.00
Base terminal wire	High alloyed Steel	Со	7440-48-4	6.868	16.51
	r light alloyed Steel	Fe	7439-89-6	21.291	51.18
		Ni	7440-02-0	11.687	28.09
		Mn	7439-96-5	0.100	0.24
		Si	7440-21-3	0.100	0.24
		C	7440-21-3 7440-44-0	0.048	0.12
	Chamical Diating	Ni		0.004	
	Chemical Plating	NI P	7440-02-0		1.04
	Coldon		7723-14-0	0.042	0.10
	Solder	Sn	7440.31-5	1.086	2.61
		Ag	7440-22-4	0.034	0.08
		Cu	7440-50-8	0.006	0.01
Cover	Conner Alley	Cu	7440 50 0	224 200	60.60
	Copper Alloy	Cu	7440-50-8	231.300	62.62
		Ni Zn	7440-02-0	60.876	16.48
		Zn	7440-66-6	66.780	18.08
		Mn	7439-96-5	0.760	0.21
	Floatro Distinct	Fe	7439-89-6	0.284	0.08
0 4 111	Electro Plating	Ni	7440-02-0	9.400	2.54
Crystal blank	Quartz	6:00	14000 00 7	07.507	04.04
	Quartz	SiO2	14808-60-7	27.567	94.84
	Silver plating	Ag	7440-22-4	1.500	5.16
Bonding Adhesive	0.1		7440.00.4	2 225	70.00
	Silver epoxy	Ag -	7440-22-4	2.800	70.00
		Epoxy resin		1.200	30.00

Material Composition Data

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Sub-Assembly Material Substance CAS No Mass (mg) Sub-Assembly % by mass

Total Mass: 843.577 mg

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